L Number	Hits	Search Text	DB	Time stamp
1	71	(coat$3 or deposit$3 or apply$3 or film or layer) with (cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (Tg or "T.sub.g")	USPAT; US-PGPUB	2004/08/30 08:14
2	86	(coat$3 or deposit$3 or apply$3 or film or layer) with (cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition)	USPAT; US-PGPUB	2004/08/30 08:39
3	5	(stress$3) with (cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition)	USPAT; US-PGPUB	2004/08/30 08:31
4	1	(relax$7) with (cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition)	USPAT; US-PGPUB	2004/08/30 08:28
5	968	(coat$3 or deposit$3 or apply$3 or film or layer) with (cure or cured or curing or harden$3 or polymeriz$6) near4 (soften$4)	USPAT; US-PGPUB	2004/08/30 08:29
6	18	(coat$3 or deposit$3 or apply$3 or film or layer) with (cure or cured or curing or harden$3 or polymeriz$6) near4 (soften$4) with (Tg or "T.sub.g" or (glass near2 transition))	USPAT; US-PGPUB	2004/08/30 08:29
7	0	(stress$3 or relax$7) with (cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition)	EPO; JPO; DERWENT; IBM_TDB	2004/08/30 08:32
8	32	(coat$3 or deposit$3 or apply$3 or film or layer) with (cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition)	EPO; JPO; DERWENT; IBM_TDB	2004/08/30 08:38
9	467	resistor with TCR	USPAT; US-PGPUB	2004/08/30 08:39
10	415	((cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition))	USPAT; US-PGPUB	2004/08/30 08:41
11	329	(((cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition))) not ((coat$3 or deposit$3 or apply$3 or film or layer) with (cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition))	USPAT; US-PGPUB	2004/08/30 08:40
12	58	((cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition)) same (stamp$5 or pattern$4 or press$3 or die or emboss$5)	USPAT; US-PGPUB	2004/08/30 08:44
13	13	((cure or cured or curing or harden$3 or polymeriz$6) near3 (higher or above or greater or hotter) near3 (glass near2 transition)) same (stamp$5 or pattern$4 or press$3 or die or emboss$5)	EPO; JPO; DERWENT; IBM_TDB	2004/08/30 08:45
14	11	(spincoat$3 or (spin adj coat$3)) with (resin$5 or monomer$3 or prepolymer$4 or solution or liquid) with (temperature) with (lower or below or under) near4 (cure or cured or curing or polymeriz$6 or harden$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 08:53
15	12	(spincoat$3 or (spin adj coat$3)) with (temperature) near3 (lower or below or under) near4 (cure or cured or curing or polymeriz$6 or harden$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 08:54

16	775	(coat$3 or deposit$3 or apply$3) near4 (temperature) near3 (lower or below or under) near3 (cure or cured or curing or polymeriz$6 or harden$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:00
17	13	(stamp$3 with substrate with (alignment adj mark$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:07
18	0	(stamp$3 with pattern$4 with (inert) with (vacuum or (low$2 adj pressure) or (reduc$5 near2 pressure)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:09
19	14	(stamp$3 with (inert) with (vacuum or (low$2 adj pressure) or (reduc$5 near2 pressure)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:10
20	1	(stamp$3 with (vacuum or (low$2 adj pressure) or (reduc$5 near2 pressure))) and ((427/277).ccls. or (427/278).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:37
21	1344455	(stamp$3 with pattern$3 (vacuum or (low$2 adj pressure) or (reduc$5 near2 pressure)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:12
22	117	(stamp$3 with pattern$3 with (vacuum or (low$2 adj pressure) or (reduc$5 near2 pressure)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:17
23	68	(stamp$3 with (vacuum adj chamber))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:28
24	74	(stamp$3 with (inert adj gas))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:40
25	0	(stamp$3 same (inert)) and ((427/277).ccls. or (427/278).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:38
26	9	((inert adj gas)) and ((427/277).ccls. or (427/278).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:38
27	171	(stamp$3 with (inert))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:40
28	97	((stamp$3 with (inert))) not ((stamp$3 with (inert adj gas)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:43
29	2	6409565.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 09:43
-	2	6759182.pn. or 6774964.pn.	USPAT; US-PGPUB	2004/08/25 13:43

–	4	(Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and ((micro adj asperity) or microasperity)	USPAT; US-PGPUB	2004/08/25 13:54
–	3	(Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and ((micro adj asperity) or microasperity)	EPO; JPO; DERWENT; IBM_TDB	2004/08/25 13:50
–	4	((Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and ((micro adj asperity) or microasperity)) and (glass near2 transition) and (decomposition)	USPAT; US-PGPUB	2004/08/25 13:57
–	1	(Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and (temperature same (polymeriz$5 or cure or curing or cured) same (glass near3 transition) same (decomposition))	USPAT; US-PGPUB	2004/08/25 13:55
–	0	(Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and (temperature and (polymeriz$5 or cure or curing or cured) and (glass near3 transition) and (decomposition))	EPO; JPO; DERWENT; IBM_TDB	2004/08/25 13:57
–	6	(Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and (temperature and (glass near3 transition) and (decomposition))	EPO; JPO; DERWENT; IBM_TDB	2004/08/25 13:56
–	54	(Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and (temperature and (polymeriz$5 or cure or curing or cured) and (glass near3 transition))	EPO; JPO; DERWENT; IBM_TDB	2004/08/25 13:57
–	4	((Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and ((micro adj asperity) or microasperity)) and (reflect$4 near3 (LCD or (liquid adj crystal$4 adj display)))	USPAT; US-PGPUB	2004/08/25 13:58
–	63	(Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and (reflect$4 near3 (LCD or (liquid adj crystal$4 adj display)))	USPAT; US-PGPUB	2004/08/25 14:08
–	19	((Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and (reflect$4 near3 (LCD or (liquid adj crystal$4 adj display)))) and ((pattern or groove or plate) with (stamp$2 or roll$3 or die))	USPAT; US-PGPUB	2004/08/25 13:59
–	19	((Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and (reflect$4 near3 (LCD or (liquid adj crystal$4 adj display)))) and ((pattern or groove or plate or asperity or microasperity) with (stamp$2 or roll$3 or die))	USPAT; US-PGPUB	2004/08/25 14:09
–	76	(Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and (reflect$4 near3 (LCD or (liquid adj crystal$4 adj display)))	EPO; JPO; DERWENT; IBM_TDB	2004/08/25 14:09
–	3	((Ikeda.in. or Funamoto.in. or Matsushita.in. or Aoyama.in. or Omron.as.) and (reflect$4 near3 (LCD or (liquid adj crystal$4 adj display)))) and ((pattern or groove or plate or asperity or microasperity) with (stamp$2 or roll$3 or die))	EPO; JPO; DERWENT; IBM_TDB	2004/08/25 14:27
–	2522	(427/162,163.1,164,165).CCLS.	USPAT; US-PGPUB	2004/08/25 14:28
–	446	(427/271).CCLS.	USPAT; US-PGPUB	2004/08/25 14:28
–	523	(427/277,278).CCLS.	USPAT; US-PGPUB	2004/08/25 14:28

–	6511	(427/372.2,374.1,375,384,385.5,389.7).CCLS.	USPAT; US-PGPUB	2004/08/25 14:28
–	1062	(264/1.31,1.1,1.34,1.9).CCLS.	USPAT; US-PGPUB	2004/08/25 14:28
–	1051	(349/67,113).CCLS.	USPAT; US-PGPUB	2004/08/25 14:29
–	0	((427/271).CCLS.) and ((349/67,113).CCLS.)	USPAT; US-PGPUB	2004/08/25 14:29
–	0	((427/277,278).CCLS.) and ((349/67,113).CCLS.)	USPAT; US-PGPUB	2004/08/25 14:29
–	0	((427/372.2,374.1,375,384,385.5,389.7).CCLS.) and ((349/67,113).CCLS.)	USPAT; US-PGPUB	2004/08/25 14:29
–	0	((264/1.31,1.1,1.34,1.9).CCLS.) and ((349/67,113).CCLS.)	USPAT; US-PGPUB	2004/08/25 14:30
–	1051	((349/67,113).CCLS.)	USPAT; US-PGPUB	2004/08/25 14:30
–	2	((427/162,163.1,164,165).CCLS.) and ((349/67,113).CCLS.)	USPAT; US-PGPUB	2004/08/25 14:31
–	34	((427/162,163.1,164,165).CCLS.) and ((427/271).CCLS.)	USPAT; US-PGPUB	2004/08/25 14:33
–	19	((427/162,163.1,164,165).CCLS.) and ((427/277,278).CCLS.)	USPAT; US-PGPUB	2004/08/25 14:34
–	63	((427/162,163.1,164,165).CCLS.) and ((264/1.31,1.1,1.34,1.9).CCLS.)	USPAT; US-PGPUB	2004/08/25 14:37
–	0	((427/277,278).CCLS.) and (reflect$5 with (LCD or (liquid adj crystal$4 adj display)))	USPAT; US-PGPUB	2004/08/25 14:38
–	4	((427/277,278).CCLS.) and ((LCD or (liquid adj crystal$4 adj display)))	USPAT; US-PGPUB	2004/08/25 14:38
–	11648	((427/162,163.1,164,165).CCLS.) ((427/271).CCLS.) ((427/277,278).CCLS.) ((427/372.2,374.1,375,384,385.5,389.7).CCLS.) ((264/1.31,1.1,1.34,1.9).CCLS.) ((349/67,113).CCLS.)	USPAT; US-PGPUB	2004/08/27 09:17
–	2	(((427/162,163.1,164,165).CCLS.) ((427/271).CCLS.) ((427/277,278).CCLS.) ((427/372.2,374.1,375,384,385.5,389.7).CCLS.) ((264/1.31,1.1,1.34,1.9).CCLS.) ((349/67,113).CCLS.)) and (microasperity or (micro adj asperity))	USPAT; US-PGPUB	2004/08/25 14:39
–	4	(microasperity or (micro adj asperity)) and (reflect$5 with (LCD or (liquid adj crystal$4 adj display)))	USPAT; US-PGPUB	2004/08/25 14:40
–	38	((349/67,113).CCLS.) and (pattern$3 with (stamp$3 or master or emboss$4 or roll$3))	USPAT; US-PGPUB	2004/08/25 14:51
–	102	(reflect$5 with (LCD or (liquid adj crystal$4 adj display))) and ((pattern$3 or resin$4 or polyimide or polymer$2) with (stamp$3 or master or emboss$4 or roll$3)) and (((427/162,163.1,164,165).CCLS.) ((427/271).CCLS.) ((427/277,278).CCLS.) ((427/372.2,374.1,375,384,385.5,389.7).CCLS.) ((264/1.31,1.1,1.34,1.9).CCLS.) ((349/67,113).CCLS.))	USPAT; US-PGPUB	2004/08/25 14:52
–	64	((reflect$5 with (LCD or (liquid adj crystal$4 adj display))) and ((pattern$3 or resin$4 or polyimide or polymer$2) with (stamp$3 or master or emboss$4 or roll$3)) and (((427/162,163.1,164,165).CCLS.) ((427/271).CCLS.) ((427/277,278).CCLS.) ((427/372.2,374.1,375,384,385.5,389.7).CCLS.) ((264/1.31,1.1,1.34,1.9).CCLS.) ((349/67,113).CCLS.))) not (((349/67,113).CCLS.) and (pattern$3 with (stamp$3 or master or emboss$4 or	USPAT; US-PGPUB	2004/08/25 14:53
–	11656	((427/162,163.1,164,165).CCLS.) ((427/271).CCLS.) ((427/277,278).CCLS.) ((427/372.2,374.1,375,384,385.5,389.7).CCLS.) ((264/1.31,1.1,1.34,1.9).CCLS.) ((349/67,113).CCLS.)	USPAT; US-PGPUB	2004/08/27 09:37
–	1	6538711.pn.	USPAT; US-PGPUB	2004/08/27 09:58

–	523	(427/277,278).CCLS.	USPAT; US-PGPUB	2004/08/27 10:00
–	16	((427/277,278).CCLS.) and (glass adj transition)	USPAT; US-PGPUB	2004/08/27 10:11
–	931	((coat$3 or deposit$3 or apply$3 or application or spincoat$3) with (temperature) with (lower or below or under) with ((polymeriz$5 or curing) near3 temperature))	USPAT; US-PGPUB	2004/08/27 10:16
–	0	(((coat$3 or deposit$3 or apply$3 or application or spincoat$3) with (temperature) with (lower or below or under) with ((polymeriz$5 or curing) near3 temperature))) and ((427/277,278).CCLS.)	USPAT; US-PGPUB	2004/08/27 10:15
–	74	(((coat$3 or deposit$3 or apply$3 or application or spincoat$3) with (temperature) with (lower or below or under) with ((polymeriz$5 or curing) near3 temperature))) and ((((427/162,163.1,164,165).CCLS.) ((427/271).CCLS.) ((427/277,278).CCLS.) ((427/372.2,374.1,375,384,385.5,389.7).CCLS.) ((264/1.31,1.1,1.34,1.9).CCLS.)	USPAT; US-PGPUB	2004/08/27 10:15
–	40	((coat$3 or deposit$3 or apply$3 or application or spincoat$3) with (temperature) with (lower or below or under) with ((polymeriz$5 or curing or reaction) near3 temperature)) and ((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near6 (glass adj transition)))	USPAT; US-PGPUB	2004/08/27 10:21
–	1	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) and ((427/277,278).CCLS.)	USPAT; US-PGPUB	2004/08/27 10:22
–	3	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) same ((press$3 or stamp$3 or roll$3 or die or master) near7 (emboss$5 or pattern$3 or concave or convex))	USPAT; US-PGPUB	2004/08/27 10:24
–	51	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) and ((press$3 or stamp$3 or roll$3 or die or master) near7 (emboss$5 or pattern$3 or concave or convex))	USPAT; US-PGPUB	2004/08/27 10:30
–	48	(((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) and ((press$3 or stamp$3 or roll$3 or die or master) near7 (emboss$5 or pattern$3 or concave or convex))) not (((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) same ((press$3 or stamp$3 or roll$3 or die or master) near7 (emboss$5 or pattern$3 or concave or convex)))	USPAT; US-PGPUB	2004/08/27 10:25
–	2	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) and ((press$3 or stamp$3 or roll$3 or die or master) near7 (emboss$5 or pattern$3 or concave or convex))	EPO; JPO; DERWENT; IBM_TDB	2004/08/27 10:29

–	189	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) same ((press$3 or stamp$3 or roll$3 or die or master or emboss$5))	USPAT; US-PGPUB	2004/08/27 11:04
–	168	(((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) same ((press$3 or stamp$3 or roll$3 or die or master or emboss$5))) not ((((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) and ((press$3 or stamp$3 or roll$3 or die or master) near7 (emboss$5 or pattern$3 or concave or convex))) not (((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) same ((press$3 or stamp$3 or roll$3 or die or master) near7 (emboss$5 or pattern$3 or concave or convex))))	USPAT; US-PGPUB	2004/08/27 10:36
–	95	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) same ((press or pressing or pressed or stamp$3 or roll$3 or die or master or emboss$5))	USPAT; US-PGPUB	2004/08/27 10:42
–	77	(((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) same ((press or pressing or pressed or stamp$3 or roll$3 or die or master or emboss$5))) not ((((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) and ((press$3 or stamp$3 or roll$3 or die or master) near7 (emboss$5 or pattern$3 or concave or convex))) not (((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) same ((press$3 or stamp$3 or roll$3 or die or master) near7 (emboss$5 or pattern$3 or concave or convex))))	USPAT; US-PGPUB	2004/08/27 10:37
–	6	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition)) with (coat$3 or deposit$4 or film or layer or apply$3 or application) with (benefi$8 or advantag$7 or prefer$6 or optim$6))	USPAT; US-PGPUB	2004/08/27 10:50
–	72	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition)) with (benefi$8 or advantag$7 or prefer$6 or optim$6))	USPAT; US-PGPUB	2004/08/27 10:57

–	66	(((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition)) with (benefi$8 or advantag$7 or prefer$6 or optim$6))) not (((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition)) with (coat$3 or deposit$4 or film or layer or apply$3 or application) with (benefi$8 or advantag$7 or prefer$6 or optim$6)))	USPAT; US-PGPUB	2004/08/27 10:46
–	344	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition)) with (coat$3 or deposit$4 or film or layer or apply$3 or application))	USPAT; US-PGPUB	2004/08/27 10:53
–	63	(((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition)) with (coat$3 or deposit$4 or film or layer or apply$3 or application))) same ($8acrylate or $8acrylic or PMMA)	USPAT; US-PGPUB	2004/08/27 10:54
–	30	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition)) with (benefi$8 or advantag$7 or prefer$6 or optim$6))	EPO; JPO; DERWENT; IBM_TDB	2004/08/27 10:57
–	40	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) with (soften$4)	USPAT; US-PGPUB	2004/08/27 11:08
–	13	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) with (soften$4)	EPO; JPO; DERWENT; IBM_TDB	2004/08/27 11:09
–	34	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) and ((coat$3 or deposit$3 or apply$3) with (monomer$3 or oligomer$2 or prepolymer$2 or (pre adj polymer$2)))	EPO; JPO; DERWENT; IBM_TDB	2004/08/30 08:05
–	42	((cure or cured or curing or harden$3 or polymeriz$5) with (temperature) with ((above or higher or greater) near5 (glass adj transition))) same ((coat$3 or deposit$3 or apply$3) with (monomer$3 or oligomer$2 or prepolymer$2 or (pre adj polymer$2)))	USPAT; US-PGPUB	2004/08/27 11:14
–	1100	((cure or cured or curing or harden$3 or polymeriz$5)) same ((coat$3 or deposit$3 or apply$3) with (monomer$3 or oligomer$2 or prepolymer$2 or (pre adj polymer$2))) same ((stamp$5 or emboss$5 or roll$4 or die or press or pressed or pressing))	USPAT; US-PGPUB	2004/08/27 11:19
–	23	((cure or cured or curing or harden$3 or polymeriz$5)) same ((coat$3 or deposit$3 or apply$3) with (monomer$3 or oligomer$2 or prepolymer$2 or (pre adj polymer$2))) same ((stamp$5 or emboss$5 or roll$4 or die or press or pressed or pressing) near6 (pattern$4 or convex or concave or indent$6))	USPAT; US-PGPUB	2004/08/27 11:17

| | | 73 | (((cure or cured or curing or harden$3 or polymeriz$5)) same ((coat$3 or deposit$3 or apply$3) with (monomer$3 or oligomer$2 or prepolymer$2 or (pre adj polymer$2))) same ((stamp$5 or emboss$5 or roll$4 or die or press or pressed or pressing))) and (((427/162,163.1,164,165).CCLS.) ((427/271).CCLS.) ((427/277,278).CCLS.) ((427/372.2,374.1,375,384,385.5,389.7).CCLS.) ((264/1.31,1.1,1.34,1.9).CCLS.) ((349/67,113).CCLS.)) | USPAT; US-PGPUB | 2004/08/27 11:19 |